

# P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)			
- 30	0.018 at V <sub>GS</sub> = - 10 V	- 40	13 nC			
- 30	0.025 at V <sub>GS</sub> = - 4.5 V	- 35	13110			

## **FEATURES**

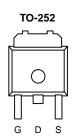
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested

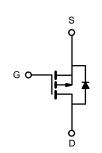
# Pb-free PoHS



### **APPLICATIONS**

- Load Switch
- · Battery Switch





P-Channel MC	JOEET

ABSOLUTE MAXIMUM RATINGS $T_A =$	= 25 °C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C		- 40	
Continuous Proin Current (T. – 150 °C)	T <sub>C</sub> = 70 °C	1 , [	- 35	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	- 30.0 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 28 <sup>a, b</sup>	Α
Pulsed Drain Current	I <sub>DM</sub>	- 150		
Continuous Courses Brain Binds Coursest	T <sub>C</sub> = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	ls –	- 2.1 <sup>a, b</sup>	
	T <sub>C</sub> = 25 °C		40	
Maximum Davier Dissipation	T <sub>C</sub> = 70 °C		27	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	VV
	T <sub>A</sub> = 70 °C		1.6 <sup>a, b</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>sta</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	24	30	C/VV	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on  $T_C = 25$  °C.



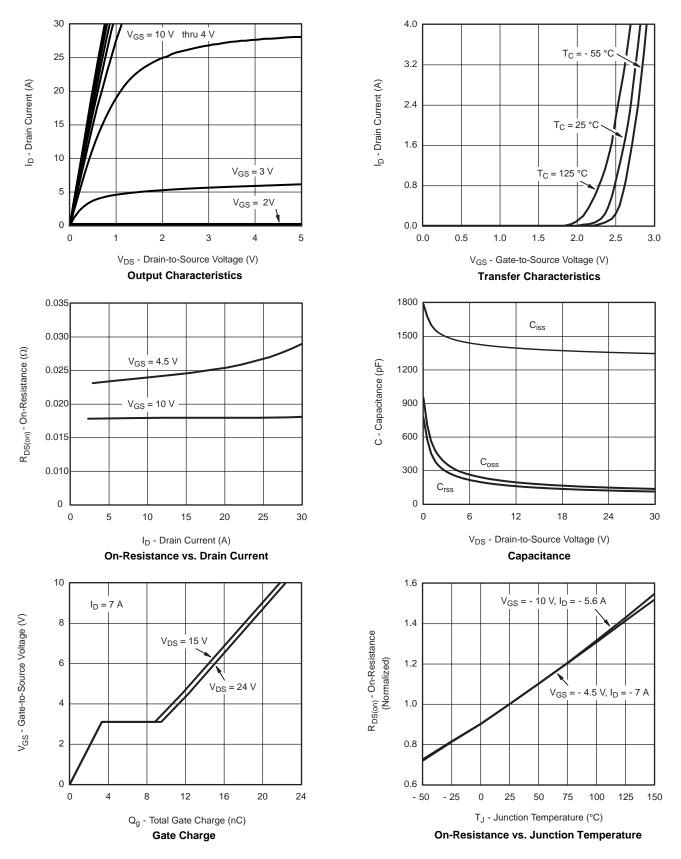
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				·			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$				V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		- 31		m\//0C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I <sub>D</sub> = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$			- 2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valta na Brain Commant	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 40			Α	
D : 0		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 7.0 A		0.018		Ω	
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.6 A		0.025			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 7.0 A		18		S	
Dynamic <sup>b</sup>							
Input Capacitance	$C_{iss}$			1455		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180			
Reverse Transfer Capacitance	C <sub>rss</sub>			145			
Total Gate Charge	Qg	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38		
			13	20			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		- nC	
Gate-Drain Charge	$Q_{gd}$			5.5			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.0	4.0	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	20		
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		13	20		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_{D} \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_{g} = 1 \Omega$		23	35	1	
Fall Time	t <sub>f</sub>			9	18		
Turn-On Delay Time	t <sub>d(on)</sub>			38	57	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 2.7 $\Omega$		89	134		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		22	33		
Fall Time	t <sub>f</sub>			11	17	1	
<b>Drain-Source Body Diode Characteris</b>	stics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6.5	۸	
Pulse Diode Forward Current	I <sub>SM</sub>				- 30	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 5.6 A, V <sub>GS</sub> = 0 V		- 0.71	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	33	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 56 A dl/dt = 100 A/up T = 25 °C		17	26	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °\text{C}$		13		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			9			

#### Notes:

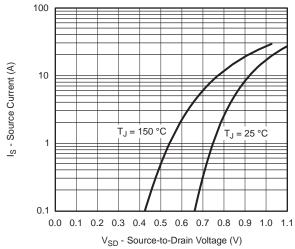
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

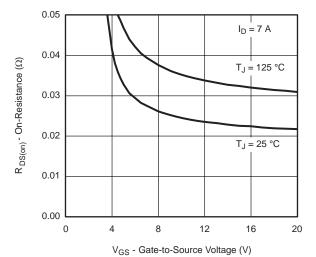




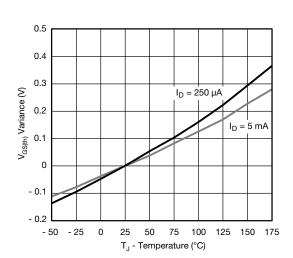




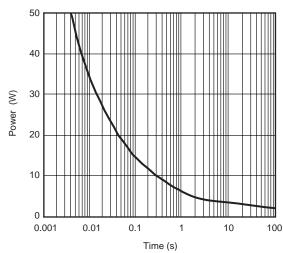
#### Source-Drain Diode Forward Voltage



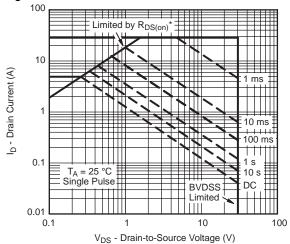
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



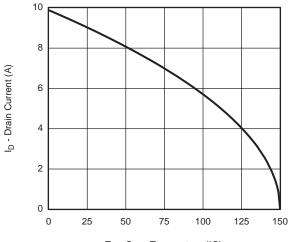
Single Pulse Power, Junction-to-Ambient



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

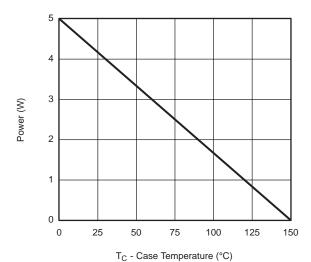
Safe Operating Area



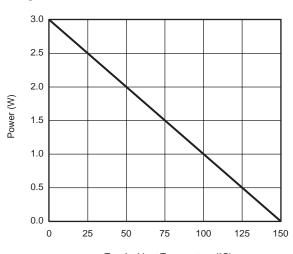


T<sub>C</sub> - Case Temperature (°C)

#### **Current Derating\***



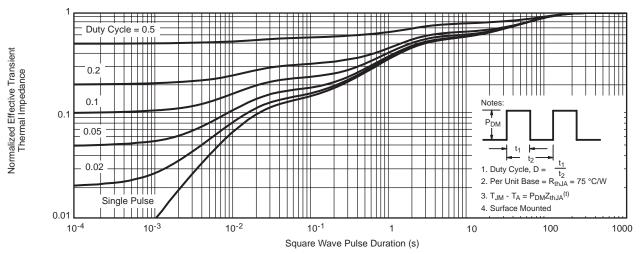
Power, Junction-to-Foot



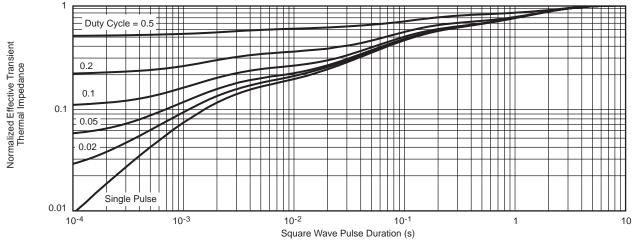
 $\label{eq:TA} \textbf{T}_A \text{ - Ambient Temperature (°C)} \\ \textbf{Power Derating, Junction-to-Ambient}$ 

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





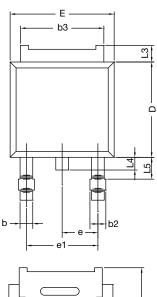
Normalized Thermal Transient Impedance, Junction-to-Ambient

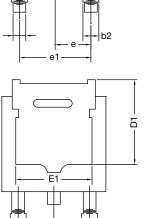


Normalized Thermal Transient Impedance, Junction-to-Foot



# **TO-252AA CASE OUTLINE**







	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12					

DWG: 5347

#### Note

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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